



## Material Content Data Sheet



Sales Product Name	IDH04S60C			Issued		2. December 2015		
MA#	MA000703442							
Package	PG-TO220-2-1			Weight*		1968.24 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.943	0.05	0.05	479	479
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		382	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
	non noble metal	copper	7440-50-8	751.797	38.20	38.25	381963	382461
wire	non noble metal	aluminium	7429-90-5	0.653	0.03	0.03	332	332
encapsulation	organic material	carbon black	1333-86-4	9.094	0.46		4620	
	plastics	epoxy resin	-	100.036	5.08		50825	
	inorganic material	silicondioxide	60676-86-0	497.151	25.26	30.80	252587	308032
leadfinish	non noble metal	tin	7440-31-5	14.668	0.75	0.75	7452	7452
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	1	101
solder	noble metal	silver	7440-22-4	0.062	0.00		32	
	non noble metal	tin	7440-31-5	0.050	0.00		25	
	non noble metal	lead	7439-92-1	2.376	0.12	0.12	1207	1264
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		300	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	copper	7440-50-8	589.466	29.95	29.99	299489	299879
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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